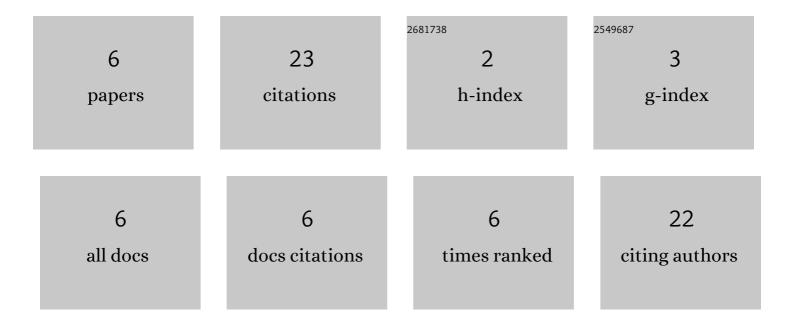


List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/6184660/publications.pdf

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#	Article	IF	CITATIONS
1	Novel polarity effect on intermetallic compound thickness changes during electromigration in Cu/Sn-3.0Ag-0.5Cu/Cu solder joints. Journal of Applied Physics, 2019, 126, .	1.1	15
2	Electromigration behavior of silver thin film fabricated by electron-beam physical vapor deposition. Journal of Materials Science, 2021, 56, 9769-9779.	1.7	6
3	Observation of void formation patterns in SnAg films undergoing electromigration and simulation using random walk methods. Scientific Reports, 2021, 11, 8668.	1.6	2
4	Failure analysis on Mobile Phone Batteries and Accessories. , 2018, , .		0
5	The voids growth path on Sn-Ag thin film under high current density. , 2021, , .		Ο
6	Electromigration Comparison Study of Sn, Ag, and Cu Stripes Fabricated by Electron-Beam Physical Vapor Deposition. , 2022, , .		0